AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended): A probe sheet unit being a sensing section of a semiconductor wafer measuring instrument comprising:

a base plate mountable to a prober of the instrument;

a sheet member mounted to the base plate; and

plural measurement probes provided on one surface of the sheet member, one end of each probe being supported by the sheet member, wherein

~~the plural measurement probes are elastically deformable respectively in response to a force acting on the top thereof for varying proximity from the top of the probe to said sheet member and~~

said sheet member is elastically deformable in response to a force acting thereon through the respective measurement probes for varying proximity therefrom to said base plate, and

~~wherein a proximity to the sheet member is variable in order to absorb and accommodate a plurality of dispersion in heights of electrodes of a measurement objective so as to accommodate inclination and warp of the measurement objective as a whole~~

each of said plural measurement probes further comprises:

a supporting portion anchored to the surface of the sheet member;

a contacting portion contactable with a measurement object and

an abutting portion abuttable with the surface of the sheet member,

the each probe being elastically deformable such that a force acting on the contacting portion by contacting with the measurement object causes the contacting portion to be displaced toward the sheet member and the abutting portion to abut the surface of the sheet member, and then the abutting portion slides in a horizontal direction on the surface of the sheet member while the contacting portion slides in the same direction as the abutting portion on the surface of the measurement object.

Claim 2 (previously presented): A probe sheet unit according to claim 1, wherein wiring patterns are formed inside and/or on a surface of the sheet member and an external electrode connected electrically to the probes through the wiring patterns is provided on the surface of the sheet member.

Claim 3 (previously presented): A probe sheet unit according to claim 2, wherein circuit elements are provided inside and/or on a surface of the sheet member and the circuit elements are connected electrically to the wiring patterns.

Claim 4 (Currently Amended): A probe sheet unit according to claim 1, wherein ~~each of the probes is curved and supported at one end thereof and~~ each probe is integrally provided with a reinforcing member with an elasticity higher than [[a]] the probe ~~is provided integrally with the probe~~ on a surface thereof facing the sheet member along the length direction.

Claim 5 (Currently amended): A probe sheet unit according to claim 1, wherein ~~each of the probes is curved and a top portion thereof is contactable with said electrodes of the measurement objective, and~~ an reinforcement member with an elasticity higher than the probe is provided on said surface of the sheet member to be located between the sheet member and ~~an opposite side of the probe from the top thereof~~ the contacting portion of the each probe.

Claim 6 (previously presented): A probe sheet unit according to claim 1, wherein the sheet member is made of a material with a linear expansion coefficient in the range of from 2.5 to 10.5 ppm/°C.

Claim 7 (previously presented): A probe sheet unit according to claim 1, wherein an elastic member interposed between the base plate and the sheet member.

Claim 8 (Canceled).